

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of)
)
Yamazaki et al.)
)
Serial No.:)
)
Filed: Herewith)
)
For: Wiring Material And A)
Semiconductor Device Having A)
Wiring Using the Material, And The)
Manufacturing Method Thereof)
)
Art Unit:)
)
Examiner:)

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Date of Deposit July 29, 2003

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Name: Yue X. Ruan
(typed or printed)

Signature Yue X. Ruan

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT A

Sir:

Prior to examination and calculation of the fees, please amend the above-identified application as follows: